30V, 125A, 2.0mΩ N-channel Power SGT MOSFET

JMSL0302PU

Features

- \bullet $\;$ Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS Tested
- 100% ΔVds Tested
- Halogen-free; RoHS-compliant
- Pb-free plating

Applications

- Load Switch
- PWM Application
- Power Management

Product Summary

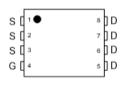
Parameters	Value	Unit		
V_{DSS}	30	V		
$V_{GS(th)_Typ}$	1.5	V		
I _D (@V _{GS} =10V)	125	Α		
$R_{DS(ON)_Typ}(@V_{GS}=10V$	1.4	mΩ		
$R_{DS(ON)_Typ}(@V_{GS}=4.5V$	2.0	mΩ		

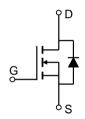












PDFN3x3-8L

Pin Assignment

Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMSL0302PU-13	SL0302P	1	Tape&Reel	PDFN3x3-8L	5000	50000

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

	<u> </u>	•	•	
Symbol	Parameter		Value	Unit
V _{DS}	Drain-to-Source Voltage	Э	30	V
V_{GS}	Gate-to-Source Voltage)	±20	V
1	Continuous Drain Current	T _C = 25°C	125	Λ
ID	Continuous Drain Current	$T_C = 100$ °C	79	A
I _{DM}	Pulsed Drain Current (1)		Refer to Fig.4	А
E _{AS}	Single Pulsed Avalanche Ene	ergy ⁽²⁾	294	mJ
P _D	Power Discipation	$T_C = 25^{\circ}C$	50	W
		$T_C = 100$ °C	20	VV
T_{J} , T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	43	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.5	C/ VV



Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					l
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics			•	•	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1	1.5	2.0	V
D	(4)	$V_{GS} = 10V, I_D = 20A$	-	1.4	2.0	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 4.5, I_D = 15A$	-	2.0	2.6	mΩ
Dynam	ic Characteristics					
R_g	Gate Resistance	f = 1MHz	-	1.7	-	Ω
C _{iss}	Input Capacitance		-	2936	4403	pF
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 15V,$ f = 1MHz	-	1716	2573	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/12	-	50	100	pF
Q_g	Total Gate Charge		-	47	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 15V, I_{D} = 20A$	-	8.5	-	nC
Q_{gd}	Gate Drain("Miller") Charge	_ VDS = 13V, ID = 20A	-	8.6	-	nC
Switchi	ing Characteristics					
$t_{d(on)}$	Turn-On DelayTime		-	10	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 15V$	-	29	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 20A, R_{GEN} = 3\Omega$	-	39	-	ns
t _f	Turn-Off Fall Time		-	11	-	ns
Body D	iode Characteristics					
I _S	Maximum Continuous Body Diode Forward Current			-	125	Α
I _{SM}	Maximum Pulsed Body Diode Forward Current		-	-	500	А
V _{SD}	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 20A$	-	_	1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 20A, di/dt = 100A/us	-	49	-	ns
Qrr	Body Diode Reverse Recovery Charge	$r_F = 20A$, $ui/ui = 100A/uS$	-	49	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

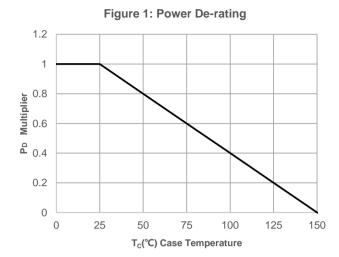
 $^{2.~}E_{AS}~condition:~Starting~T_J=25C,~V_{DD}=30V,~V_{GS}=10V,~R_G=25ohm,~L=3mH,~I_{AS}=14A,~V_{DD}=0V~during~time~in~avalanche.$

^{3.} $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB.

^{4.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.



Typical Performance Characteristics



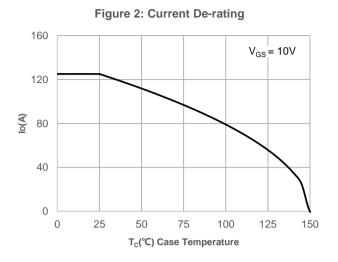
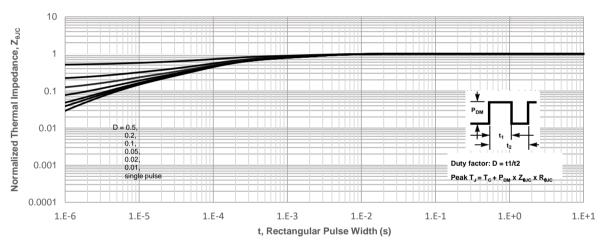
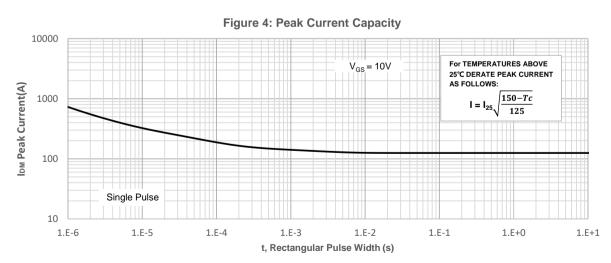


Figure 3: Normalized Maximum Transient Thermal Impedance







Typical Performance Characteristics

Figure 5: Output Characteristics

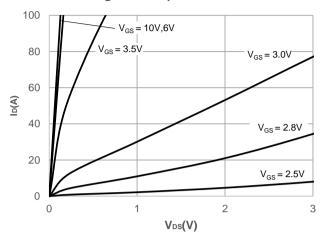


Figure 6: Typical Transfer Characteristics

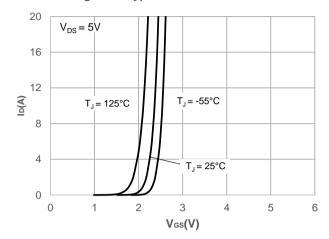


Figure 7: On-resistance vs. Drain Current

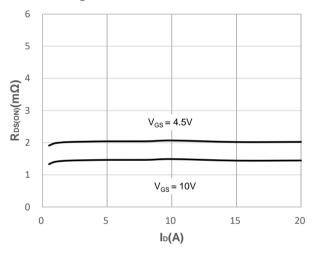


Figure 8: Body Diode Characteristics

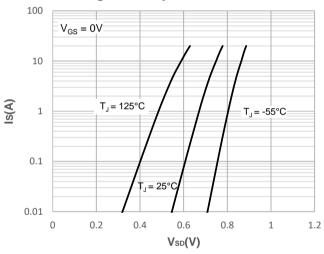


Figure 9: Gate Charge Characteristics

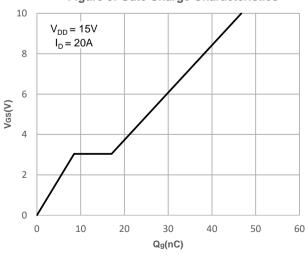
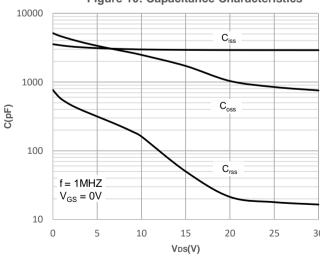


Figure 10: Capacitance Characteristics





Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

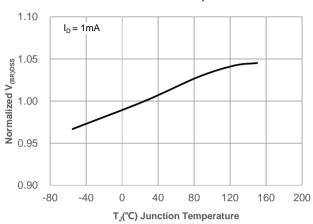


Figure 13: Normalized Threshold Voltage vs.
Junction Temperature

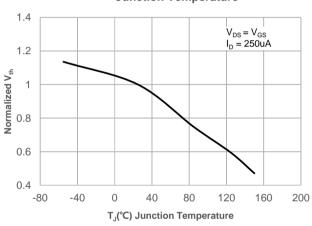


Figure 15: Maximum Safe Operating Area

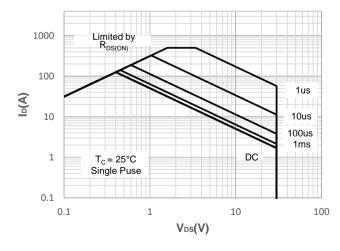
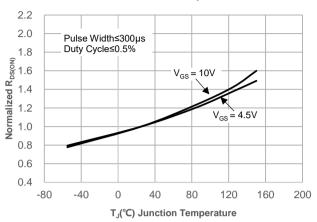
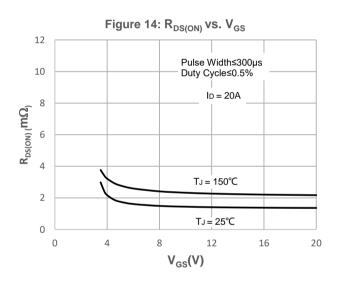


Figure 12: Normalized on Resistance vs.
Junction Temperature







Test Circuit

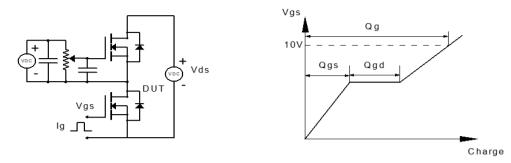


Figure 1: Gate Charge Test Circuit & Waveform

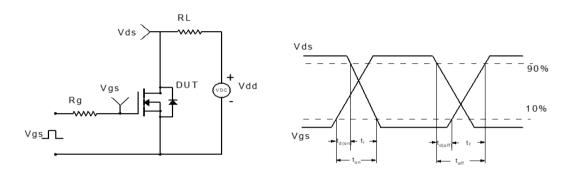


Figure 2: Resistive Switching Test Circuit & Waveform

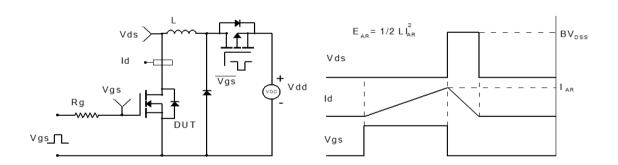


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

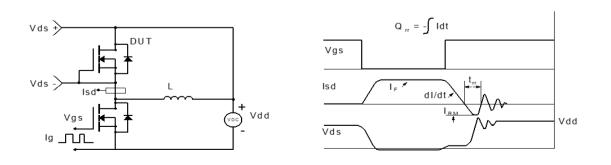
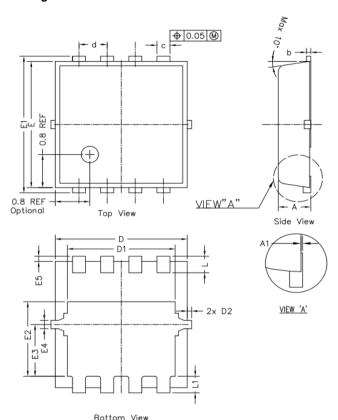


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(PDFN3x3-8L)

Package Outline



SYMBOLS	DIMENSION IN MM		DIMENSION IN INCHES			
STIVIBULS	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.700	0.750	0.800	0.028	0.030	0.031
A1			0.050			0.002
b	0.144	0.152	0.202	0.006	0.006	0.008
С	0.250	0.300	0.350	0.010	0.012	0.014
d	0.65 BSC			0.026 BSC		
D	2.950	3.050	3.150	0.116	0.120	0.124
D1	2.390	2.490	2.590	0.094	0.098	0.102
D2			0.125			0.005
E	2.950	3.050	3.150	0.116	0.120	0.124
E1	3.200	3.300	3.400	0.126	0.130	0.134
E2	1.700	1.800	1.900	0.067	0.071	0.075
E3	1.150	1.250	1.350	0.045	0.049	0.053
E4	0.150	0.200	0.250	0.006	0.008	0.010
E5	0.075	0.125	0.175	0.003	0.005	0.007
L	0.300	0.400	0.500	0.01	0.02	0.02
L1	0.300	0.400	0.500	0.01	0.02	0.02

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